

TDS

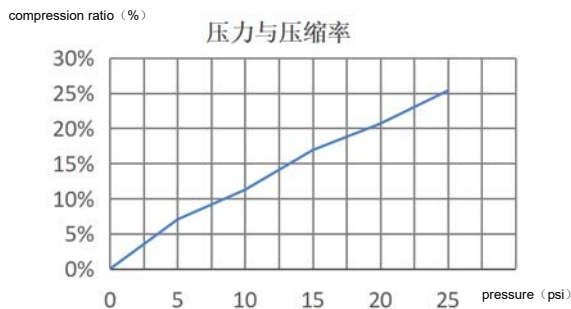


K-HC5200E is a non substrate thermal conductive silicone pad with enhanced tensile and tear resistance. It has low density, excellent electrical insulation performance, aging resistance, hydrophobic shock absorption, high and low temperature resistance, and good adhesion. It is specially customized for the heat dissipation requirements of automotive new energy power battery modules, fully filling various rough surfaces. This product comes with its own adhesive properties No need for adhesive backing to meet assembly and bonding requirements, high elasticity ensures repeated bonding during the assembly process without deformation.

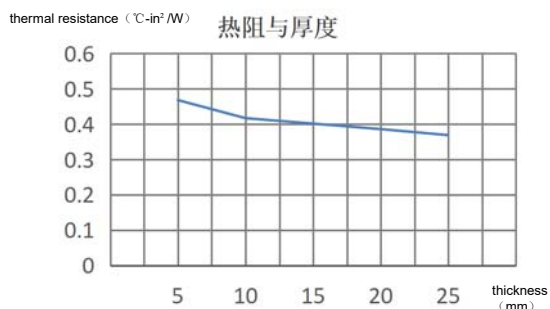
peculiarity

- Heat conductivity =2.0W/mk
- High adhesion, ultra-low hardness, suitable for low tightening pressure
- Fire protection meets V0, environmental protection meets ROHS requirements
- Resistance to puncturing, shearing and tearing

Compression graph



Thermal resistance diagram



Symbol properties		
properties of products	test value	test method
colour	grey	Visual
Thickness rang(mm)	0.3 -10.0	ASTM D374
density(g/cm ³)	2.3±0.2	ASTM D792
hardness (Shore C)	20-50(±5)	ASTM D2240
break down voltage (KV/AC)	>8	ASTM D149
dielectric constant (1.2MHz)	≥5.5	ASTM D150
mass resistivity(Ω.cm)	≥1.0*10 ¹³	ASTM D257
continuous use Temp(°C)	-40 ~ 200	EN344
weight loss(%)	≤1	@180°C 4H
fire rating	V0	UL 94
heat conductivity coefficient (W/m-K)	≥2.0	ASTM D5470

Thickness tolerance ≤ 10% of product thickness

typical application

Communications industry

Computer and peripheral power converters

Between semiconductor or magnetic body and heat sink

An area where a frame, chassis, or other heat transmitter requires heat transfer

OfferSpecification: sheet, die cutting

standard thickness mm: 1.0, 1.5, 2.0, 2.5, 3.0 Other thicknesses need to be customized;

Parallel Deviation mm: 200*400, Other sizes need to be customized;

storage condition: temperature≤40°C , humidity≤70%RH;

Note: Please refer to the MSDS report for the safety data of the product. The data in this paper are obtained under laboratory conditions. Due to the differences in the conditions of use, users need to refer to these data and conditions of use for analysis and testing. The company does not guarantee the sale of this product and the use of the company's products under specific conditions of the problem, does not assume any direct, indirect or accidental loss liability. Users can contact the technical service department across the company if they encounter any problems in the use process.